



Material Content Data Sheet



Sales Product Name		TLS203B0EJV		Issued		31. July 2018		
MA#		MA001137132						
Package		PG-DSO-8-52		Weight*		83.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.268	1.51	1.51	15137	15137
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		434	
	non noble metal	iron	7439-89-6	0.728	0.87		8687	
wire	non noble metal	copper	7440-50-8	29.548	35.27	36.19	352720	361950
	non noble metal	copper	7440-50-8	0.079	0.09	0.09	949	949
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1199
encapsulation	plastics	epoxy resin	-	4.620	5.52		55153	
	inorganic material	silicondioxide	60676-86-0	45.499	54.33	59.97	543140	599492
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8298	8298
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8649	8649
glue	plastics	epoxy resin	-	0.116	0.14		1381	
	noble metal	silver	7440-22-4	0.347	0.41	0.55	4144	5525
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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